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- Complete PWM Power-Control Function
- Totem-Pole Outputs for 200-mA Sink or Source Current
- Output Control Selects Parallel or Push-Pull Operation
- Internal Circuitry Prohibits Double Pulse at Either Output
- Variable Dead-Time Provides Control Over Total Range
- Internal Regulator Provides a Stable 5-V Reference Supply, Trimmed to 1% Tolerance
- On-Board Output Current-Limiting Protection
- Undervoltage Lockout for Low-V<sub>CC</sub>
   Conditions
- Separate Power and Signal Grounds

#### D OR N PACKAGE (TOP VIEW) ERROR J 1IN+ 16 2IN+ LERROR AMP 1 Ì 1IN− [ FEEDBACK **1** 3 14 | REF DTC 🛮 4 13 OUTPUT CTRL 12 VCC CT $\prod 5$ 11 VC RT [ SIGNAL GND 7 10 POWER GND OUT1 9 OUT2

#### description/ordering information

The TL598 incorporates all the functions required in the construction of pulse-width-modulated (PWM) controlled systems on a single chip. Designed primarily for power-supply control, the TL598 provides the systems engineer with the flexibility to tailor the power-supply control circuits to a specific application.

The TL598 contains two error amplifiers, an internal oscillator (externally adjustable), a dead-time control (DTC) comparator, a pulse-steering flip-flop, a 5-V precision reference, undervoltage lockout control, and output control circuits. Two totem-pole outputs provide exceptional rise- and fall-time performance for power FET control. The outputs share a common source supply and common power ground terminals, which allow system designers to eliminate errors caused by high current-induced voltage drops and common-mode noise.

The error amplifier has a common-mode voltage range of 0 V to  $V_{CC}$  – 2 V. The DTC comparator has a fixed offset that prevents overlap of the outputs during push-pull operation. A synchronous multiple supply operation can be achieved by connecting RT to the reference output and providing a sawtooth input to CT.

The TL598 device provides an output control function to select either push-pull or parallel operation. Circuit architecture prevents either output from being pulsed twice during push-pull operation. The output frequency

for push-pull applications is one-half the oscillator frequency  $\left(f_{\text{O}} = \frac{1}{2 \; \text{RT CT}}\right)$ . For single-ended applications:

$$f_0 = \frac{1}{RT CT}$$

#### ORDERING INFORMATION

TA	PACKAGET		ORDERABLE PART NUMBER	TOP-SIDE MARKING
	PDIP (N)	Tube of 25	TL598CN	TL598CN
0°C to 70°C	SOIC (D)	Tube of 40	TL598CD	TI 500C
	SOIC (D)	Reel of 2500	TL598CDR	TL598C

<sup>†</sup> Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



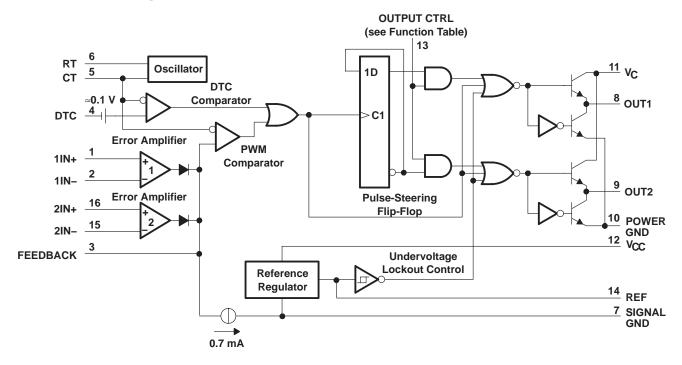
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#### **FUNCTION TABLE**

INPUT/OUTPUT CTRL	OUTPUT FUNCTION
$V_I = GND$	Single-ended or parallel output
V <sub>I</sub> = REF	Normal push-pull operation

#### functional block diagram



## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V <sub>CC</sub> (see Note 1)	41 V
Amplifier input voltage, V <sub>I</sub>	$V_{CC} + 0.3 V$
Collector voltage	41 V
Output current (each output), sink or source, IO	250 mA
Package thermal impedance, θ <sub>JA</sub> (see Notes 2 and 3): D package	
N package	67°C/W
Operating virtual junction temperature, T <sub>J</sub>	150°C
Storage temperature range, T <sub>sto</sub>	

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. All voltage values, except differential voltages, are with respect to the signal ground terminal.
  - 2. Maximum power dissipation is a function of  $T_J(max)$ ,  $\theta_{JA}$ , and  $T_A$ . The maximum allowable power dissipation at any allowable ambient temperature is  $P_D = (T_J(max) T_A)/\theta_{JA}$ . Operating at the absolute maximum  $T_J$  of 150°C can impact reliability.
  - 3. The package thermal impedance is calculated in accordance with JESD 51-7.



#### recommended operating conditions

		MIN	MAX	UNIT
Vcc	Supply voltage	7	40	V
VI	Amplifier input voltage	0	V <sub>CC</sub> -2	V
IO	Collector voltage		40	V
IIL	Output current (each output), sink or source		200	mA
	Current into feedback terminal		0.3	mA
CT	Timing capacitor	0.00047	10	μF
R <sub>T</sub>	Timing resistor	1.8	500	kΩ
fosc	Oscillator frequency	1	300	kHz
TA	Operating free-air temperature	0	70	°C

# electrical characteristics over recommended operating free-air temperature range, $V_{CC} = 15 \text{ V}$ (unless otherwise noted)

#### reference section (see Note 4)

PARAMETER	TEST CONDITIONS†		MIN	TYP‡	MAX	UNIT
Output voltage (REE)	1 4 4	T <sub>A</sub> = 25°C	4.95	5	5.05	
Output voltage (REF)	$I_O = 1 \text{ mA}$	T <sub>A</sub> = full range	4.9		5.1	V
Input regulation	V <sub>CC</sub> = 7 V to 40 V	T <sub>A</sub> = 25°C		2	25	mV
0		T <sub>A</sub> = 25°C		1	15	\/
Output regulation	$I_O = 1 \text{ mA to } 10 \text{ mA}$	T <sub>A</sub> = full range			50	mV
Output voltage change with temperature	$\Delta T_A = MIN \text{ to MAX}$			2	10	mV/V
Short-circuit output current§	REF = 0 V		-10	-48	·	mA

<sup>†</sup> Full range is 0°C to 70°C.

NOTE 4: Pulse-testing techniques that maintain the junction temperature as close to the ambient temperature as possible must be used.

#### oscillator section, $C_T = 0.001 \,\mu\text{F}$ , $R_T = 12 \,\text{k}\Omega$ (see Figure 1) (see Note 4)

	1 (300 1 iguilo 1) (300 11310 1)			
PARAMETER	TEST CONDITIONS†	MIN TYP‡	MAX	UNIT
Frequency		100		kHz
Standard deviation of frequency¶	All values of V <sub>CC</sub> , C <sub>T</sub> , R <sub>T</sub> , T <sub>A</sub> constant	100		Hz/kHz
Frequency change with voltage	$V_{CC} = 7 \text{ V to } 40 \text{ V}, \qquad T_A = 25^{\circ}\text{C}$	1	10	Hz/kHz
Frequency change with temperature#	$\Delta T_A = \text{full range}$	70	120	Hz/kHz
Frequency change with temperature"	$\Delta T_A$ = full range, $C_T$ = 0.01 $\mu F$	50	80	П2/КП2

<sup>†</sup> Full range is 0°C to 70°C.

$$\sigma = \sqrt{\frac{\sum_{n=1}^{N} (x_n - \overline{X})^2}{N-1}}$$

# Effects of temperature on external R<sub>T</sub> and C<sub>T</sub> are not taken into account.

NOTE 4. Pulse-testing techniques that maintain the junction temperature as close to the ambient temperature as possible must be used.



<sup>‡</sup> All typical values, except for parameter changes with temperature, are at T<sub>A</sub> = 25°C.

<sup>§</sup> Duration of the short circuit should not exceed one second.

 $<sup>\</sup>ddagger$  All typical values, except for parameter changes with temperature, are at  $T_A = 25$ °C.

 $<sup>\</sup>P$  Standard deviation is a measure of the statistical distribution about the mean, as derived from the formula:

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#### electrical characteristics over recommended operating free-air temperature range, V<sub>CC</sub> = 15 V (unless otherwise noted) (continued)

#### error amplifier section (see Note 4)

PARAMETER	TEST	CONDITIONS		MIN	TYP <sup>†</sup>	MAX	UNIT
Input offset voltage	FEEDBACK = 2.5 V				2	10	mV
Input offset current	FEEDBACK = 2.5 V				25	250	nA
Input bias current	FEEDBACK = 2.5 V				0.2	1	μΑ
Common-mode input voltage range	V <sub>CC</sub> = 7 V to 40 V			0 to V <sub>CC</sub> -2			V
Open-loop voltage amplification	$\Delta V_{O}$ (FEEDBACK) = 3 V,	VO (FEEDBACK	() = 0.5 V to 3.5 V	70	95		dB
Unity-gain bandwidth					800		kHz
Common-mode rejection ratio	$V_{CC} = 40 \text{ V},$	$\Delta V_{IC} = 6.5 V$ ,	T <sub>A</sub> = 25°C	65	80		dB
Output sink current (FEEDBACK)	FEEDBACK = 0.5 V			0.3	0.7		mA
Output source current (FEEDBACK)	FEEDBACK = 3.5 V			-2			mA
Phase margin at unity gain	FEEDBACK = 0.5 V to 3.5	V,	R <sub>L</sub> = 2 kΩ		65°		
Supply-voltage rejection ratio	FEEDBACK = 2.5 V,	$\Delta V_{CC} = 33 \text{ V},$	$R_L = 2 k\Omega$		100		dB

<sup>&</sup>lt;sup>†</sup> All typical values, except for parameter changes with temperature, are at  $T_A = 25^{\circ}C$ .

#### electrical characteristics over recommended operating free-air temperature range, V<sub>CC</sub> = 15 V (unless otherwise noted)

#### undervoltage lockout section (see Note 4)

PARAMETER	TEST CONDITIONS‡	MIN	MAX	UNIT	
T	T <sub>A</sub> = 25°C	4	6	T	
Threshold voltage	$\Delta T_A = \text{full range}$	3.5	6.9	V	
Lhatarais	T <sub>A</sub> = 25°C	100		m)/	
Hysteresis§	T <sub>A</sub> = full range	50		mV	

Full range is 0°C to 70°C.

#### output section (see Note 4)

PARAMETER	TEST CO	ONDITIONS	MIN	MAX	UNIT
High lovel output veltage	V <sub>CC</sub> = 15 V, V <sub>C</sub> = 15 V	$I_0 = -200 \text{ mA}$	12		.,
High-level output voltage	$V_{C} = 15 \text{ V}$	$I_0 = -20 \text{ mA}$	13		V
Level and automotive trans	V <sub>CC</sub> = 15 V, V <sub>C</sub> = 15 V	I <sub>O</sub> = 200 mA		2	
Low-level output voltage	V <sub>C</sub> = 15 V	I <sub>O</sub> = 20 mA		0.4	٧
Output control input ourront	$\forall_i = \forall_{ref}$			3.5	mA
Output-control input current	$V_I = V_{ref}$ $V_I = 0.4 V$			100	μΑ

NOTE 4. Pulse-testing techniques must be used that maintain the junction temperature as close to the ambient temperature as possible.



NOTE 4. Pulse-testing techniques that maintain the junction temperature as close to the ambient temperature as possible must be used.

<sup>\$</sup> Hysteresis is the difference between the positive-going input threshold voltage and the negative-going input threshold voltage.

NOTE 4. Pulse-testing techniques must be used that maintain the junction temperature as close to the ambient temperature as possible.

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# electrical characteristics over recommended operating free-air temperature range, $V_{CC} = 15 \text{ V}$ (unless otherwise noted) (continued)

#### dead-time control section (see Figure 1) (see Note 4)

PARAMETER	TEST CONDITIONS	MIN	TYP†	MAX	UNIT
Input bias current (DTC)	V <sub>I</sub> = 0 to 5.25 V		-2	-10	μΑ
Maximum duty cycle, each output	DTC = 0 V	0.45			
Input threshold voltage (DTC)	Zero duty cycle		3	3.3	V
Imput tilleshold voltage (DTC)	Maximum duty cycle	0			V

 $<sup>^\</sup>dagger$  All typical values, except for parameter changes with temperature, are at  $T_A = 25^\circ C$ .

#### pwm comparator section (see Note 4)

PARAMETER	TEST CONDITIONS	MIN	TYP <sup>†</sup>	MAX	UNIT
Input threshold voltage (FEEDBACK)	DTC = 0 V		3.75	4.5	V
Input sink current (FEEDBACK)	V(FEEDBACK) = 0.5 V	0.3	0.7		mA

 $<sup>^{\</sup>dagger}$  All typical values, except for parameter changes with temperature, are at  $T_A = 25^{\circ}C$ .

NOTE Pulse-testing techniques must be used that maintain the junction temperature as close to the ambient temperature as possible.

#### total device (see Figure 1) (see Note 4)

PARAMETER	TEST CONDITIONS		MIN	TYP <sup>†</sup>	MAX	UNIT
Ot a seller a second of	$RT = V_{ref}$	V <sub>CC</sub> = 15 V		15	21	4
Standby supply current	All other inputs and outputs open	V <sub>CC</sub> = 40 V		20	26	mA
Average supply current	DTC = 2 V			15		mA

 $<sup>^\</sup>dagger$  All typical values, except for parameter changes with temperature, are at T<sub>A</sub> = 25°C.

## switching characteristics, $T_A = 25^{\circ}C$ (see Note 4)

PARAMETER		TEST COND	MIN	TYP	MAX	UNIT	
Output-voltage rise time	CL = 1500 pF,	VC = 15 V,	VCC = 15 V,		60	150	20
Output-voltage fall time	See Figure 2				35	75	ns

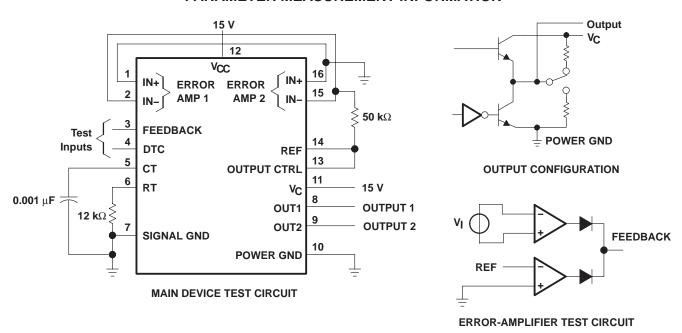
NOTE 4. Pulse-testing techniques must be used that maintain the junction temperature as close to the ambient temperature as possible.



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#### PARAMETER MEASUREMENT INFORMATION



**Figure 1. Test Circuits** 

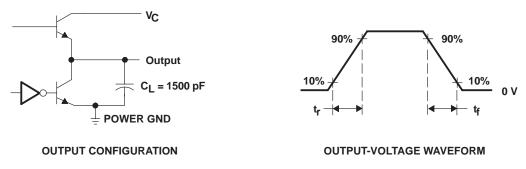
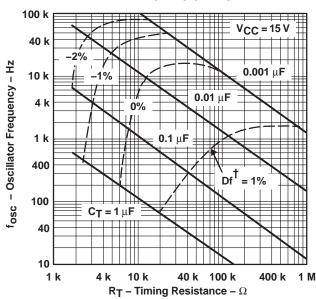


Figure 2. Switching Output Configuration and Voltage Waveform

#### **TYPICAL CHARACTERISTICS**

# OSCILLATOR FREQUENCY AND FREQUENCY VARIATION TO VS TIMING RESISTANCE



<sup>†</sup> Frequency variation ( $\Delta f$ ) is the change in predicted oscillator frequency that occurs over the full temperature range.

Figure 3

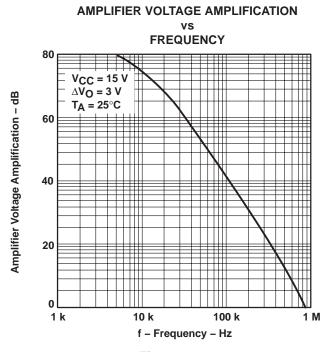


Figure 4



#### PACKAGE OPTION ADDENDUM



10-Dec-2020

#### **PACKAGING INFORMATION**

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
TL598CD	ACTIVE	SOIC	D	16	40	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	TL598C	Samples
TL598CDR	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	TL598C	Samples
TL598CN	ACTIVE	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	TL598CN	Samples
TL598CNE4	ACTIVE	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	TL598CN	Samples

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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#### **PACKAGE OPTION ADDENDUM**

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#### TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

#### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

Device		Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TL598CDR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1





#### \*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TL598CDR	SOIC	D	16	2500	333.2	345.9	28.6

# N (R-PDIP-T\*\*)

## PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



# D (R-PDS0-G16)

#### PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AC.



# D (R-PDSO-G16)

## PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



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